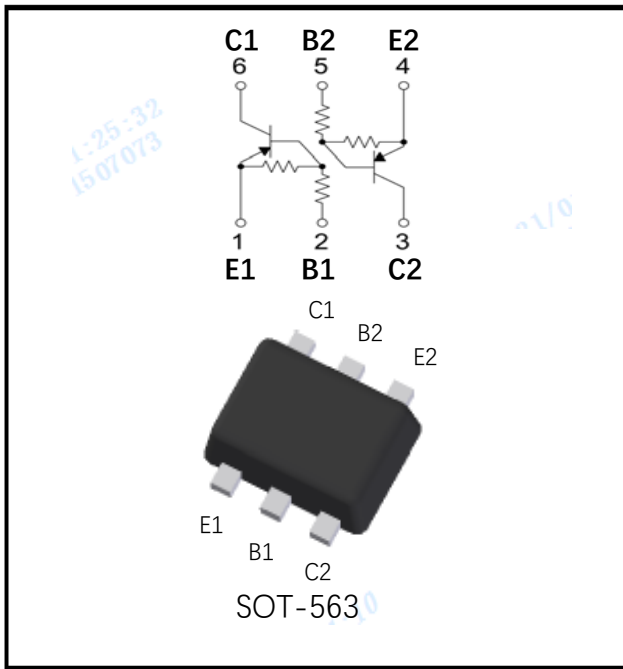


Dual PNP Digital Transistors (Built-in Resistors)



Features

- Epoxy meets UL-94 V-0 flammability rating
- Surface mount package ideally Suited for Automatic Insertion
- PNP+PNP

Mechanical Data

- **Package:** SOT-563
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Marking:** B1
- **Solid point:** E1 positioning point

■Maximum Ratings (Ta=25°C Unless otherwise specified)

Item	Symbol	Unit	Conditions	Value
Supply Voltage	V_{CC}	V		-50
Input Voltage	V_{IN}	V		-40 to +10
Output Current	I_o	mA		-100
Power Dissipation	P_D	mW		150
Junction Temperature	T_j	°C		150
Storage Temperature	T_{STG}	°C		-55 to +150



EMB1

■ Electrical Characteristics (Ta=25°C unless otherwise specified)

Item	Symbol	Unit	Conditions	Min	TYP	Max
Input voltage	$V_{I(off)}$	V	$V_{CC}=-5V, I_c=-100\mu A$	-0.5	-	-
	$V_{I(on)}$	V	$V_o=-0.2V, I_c=-5mA$	-	-	-3
Output voltage	$V_{O(on)}$	V	$I_o / I_i = -10mA / -0.5 mA$	-	-	-0.3
Input current	I_i	mA	$V_i = -5V$	-	-	-0.36
Output current	$I_{O(off)}$	uA	$V_{CC} = -50V, V_i = 0$	-	-	-0.5
DC current gain	G_i		$V_o = -5V, I_o = -5mA$	56	-	-
Input resistance	R_1	k Ω		15.4	22	28.6
Resistance ratio	R_2/R_1			0.8	1	1.2
Transition frequency	f_T	MHz	$V_{CE} = -10V, I_E = -5mA, f = 100MHz$	-	250	-

■ Ordering Information (Example)

Preferred P/N	Packing Code	Unit Weight(G)	Minimum Package(Pcs)	Inner Box Quantity(Pcs)	Outer Carton Quantity(Pcs)	Delivery Mode
EMB1	F2	Approximate 0.0035	3000	30000	120000	7" reel



■ Characteristics (Typical)

Fig. 1 - DC Current Gain Characteristics

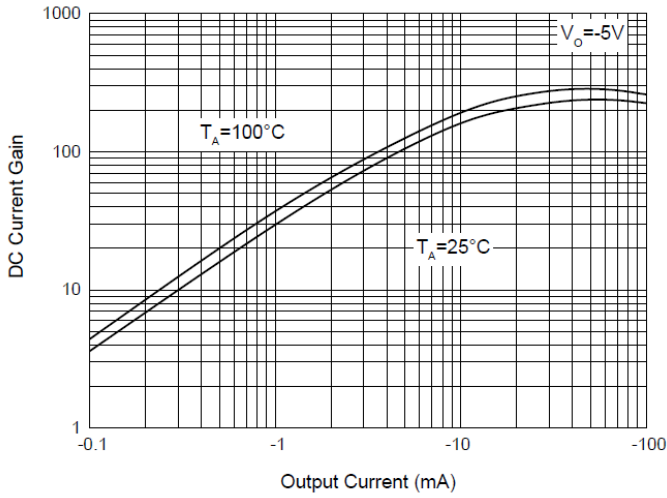


Fig. 2 - Input Voltage (on) Characteristics

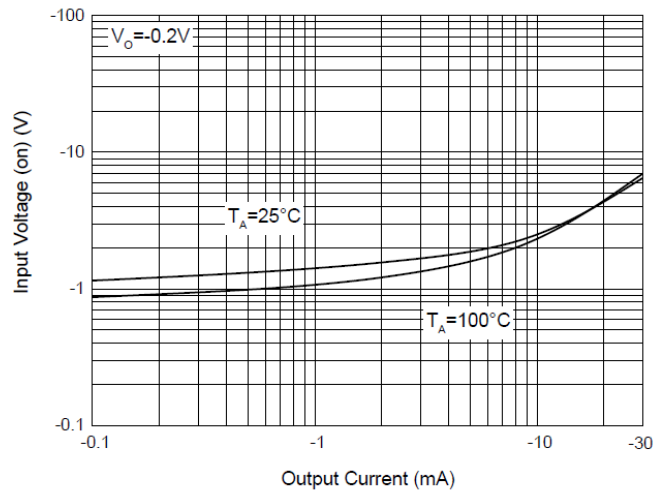


Fig. 3 - Input Voltage (off) Characteristics

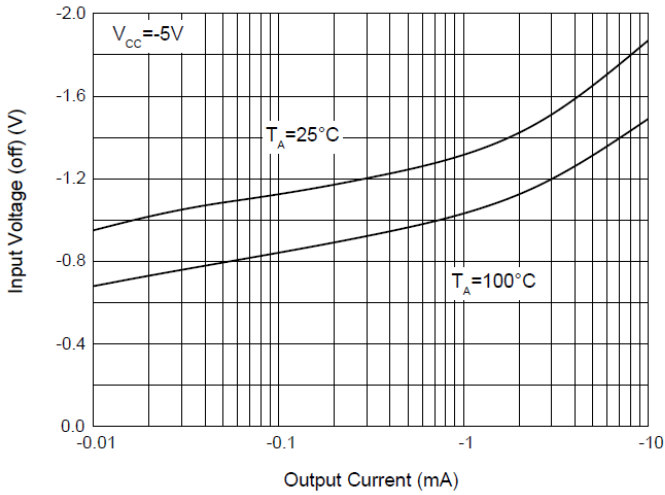
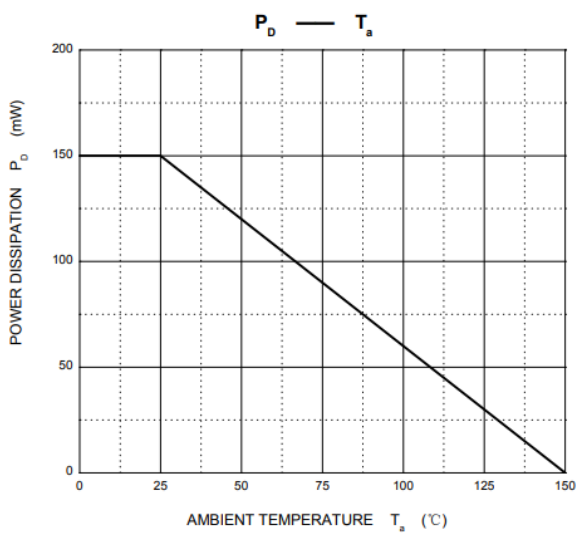
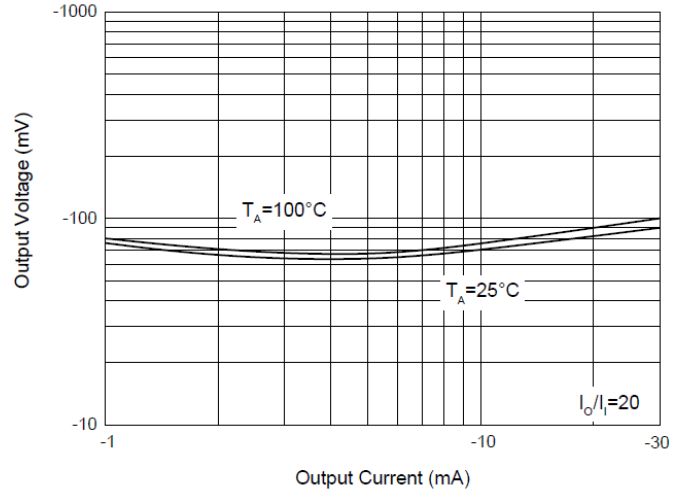
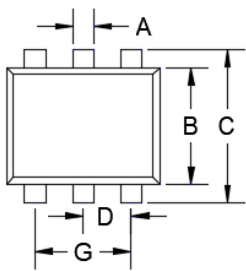


Fig. 4 - Output Voltage Characteristics

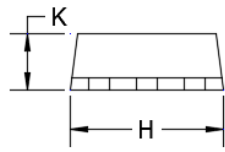


■ Outline Dimensions

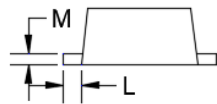
SOT-563



TOP VIEW



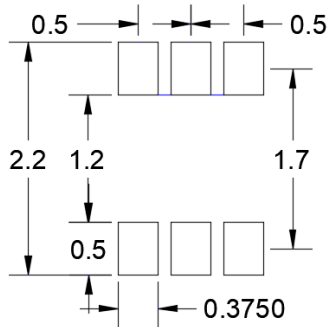
SIDE VIEW



SIDE VIEW

DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	0.006	0.011	0.150	0.300
B	0.043	0.051	1.100	1.300
C	0.059	0.067	1.500	1.700
D	0.016	0.024	0.400	0.600
G	0.035	0.043	0.900	1.100
H	0.059	0.067	1.500	1.700
K	0.021	0.026	0.550	0.650
L	0.004	0.011	0.100	0.300
M	0.004	0.007	0.100	0.180

■ Suggested Pad Layout



单位: mm

SUGGESTED SOLDER PAD LAYOUT



EMB1

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